

CLAIM AMENDMENTS:

Please amend Claims 34 and 55 as follows, cancel Claims 32 and 33, and add new Claims 56-67, as follows.

1.-22. (Cancelled)

23. (Previously Presented) The imaging apparatus according to Claim 55, wherein the wavelength converting member comprises a fluorescent member.

24. (Previously Presented) The imaging apparatus according to Claim 55, wherein the conductive member comprises an insulating base and a conductive layer provided thereon.

25. (Previously Presented) The imaging apparatus according to Claim 55, wherein the conductive member comprises a metal.

26. (Previously Presented) The imaging apparatus according to Claim 25, wherein the metal comprises aluminum.

27. (Cancelled)

28. (Previously Presented) The imaging apparatus according to Claim 55, wherein an area of the conductive member overlaps said photoelectric conversion elements.

29. (Previously Presented) The imaging apparatus according to Claim 55, wherein a periphery of the conductive member is sealed.

30. (Previously Presented) The imaging apparatus according to Claim 55, wherein a periphery of the conductive member extends over the outer edges of the and an edge portion of said conductive member is sealed so as to cover the outer edges of the plurality of substrates.

31. (Previously Presented) The imaging apparatus according to Claim 30, wherein a space is formed between the outer edges of said plurality of substrates and the conductive member.

32. (Cancelled)

33. (Cancelled)

34. (Currently Amended) The imaging apparatus according to Claim 55, wherein a the resin is provided ~~which covers~~ so as to cover a peripheral portion of said plurality of substrates and all ~~the~~ end faces of the conductive member.

35. (Previously Presented) The imaging apparatus according to Claim 55, wherein the plurality of photoelectric conversion elements are arranged in a matrix.

36. (Previously Presented) The imaging apparatus according to Claim 26, wherein the metal has a thickness of 100 μm or less.

37. - 54. (Cancelled)

55. (Currently Amended) An imaging apparatus comprising:
a photoelectric conversion device having a plurality of substrates each having a plurality of photoelectric conversion elements, the plurality of substrates being

arranged adjacent each other in a plane, and a wavelength converting member arranged on the photoelectric conversion elements over the plurality of substrates;

a control circuit for driving the device;

a housing for said photoelectric device and said control circuit; ~~and~~

a grounded conductive member disposed between said housing and said wavelength converting member; and

a resin that seals at least a portion of said plurality of substrates and at least a part of an end face of the conductive member wherein said plurality of substrates and the conductive member are in close proximity with each other.

56. (New) An imaging apparatus comprising:

a photoelectric conversion device having a plurality of photoelectric conversion elements on a panel;

a wavelength converting member arranged on the photoelectric conversion elements;

a grounded conductive member arranged on the wavelength converting member; and

a resin that seals at least a portion of the panel and at least a part of an end face of the conductive member wherein the panel and the conductive member are in close proximity with each other.

57. (New) The imaging apparatus according to Claim 56, wherein the wavelength converting member comprises a fluorescent member.

58. (New) The imaging apparatus according to Claim 56, wherein the conductive member comprises a metal.

59. (New) The imaging apparatus according to Claim 58, wherein the metal comprises aluminum.

60. (New) The imaging apparatus according to Claim 56, wherein an area of the conductive member overlaps said photoelectric conversion elements.

61. (New) The imaging apparatus according to Claim 56, wherein a periphery of the conductive member is sealed.

62. (New) The imaging apparatus according to Claim 56, wherein a periphery of the conductive member extends over the outer edges of the panel and an edge portion of said conductive member is sealed so as to cover the outer edges of the panel.

63. (New) The imaging apparatus according to Claim 62, wherein a space is formed between the outer edge of the panel and the conductive member.

64. (New) The imaging apparatus according to claim 56, wherein the resin is provided so as to cover a peripheral portion of the panel and all the end faces of the conductive member.

65. (New) The imaging apparatus according to Claim 56, wherein the plurality of photoelectric conversion elements are arranged in a matrix.

66. (New) The imaging apparatus according to Claim 58, wherein the metal has a thickness of 100 μm or less.

67. (New) The imaging apparatus according to Claim 58, wherein the panel comprises a plurality of substrates arranged adjacent each other in a plane.